EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	245	134/172.ccls. and (rotat$3 or rotary) with (nozzle or arm or manifold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:25
L8	3241	(semiconductor or wafer or substrate or workpiece) and rotor and (nozzle or arm or sprayarm or manifold) with (rotat$3 or rotary)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:25
L9	1302	(semiconductor or wafer or substrate or workpiece) and rotor and (nozzle or arm or sprayarm or manifold) near2 (rotat$3 or rotary)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 11:19
L10	230	(semiconductor or wafer or substrate or workpiece) and rotor with (nozzle or arm or sprayarm or manifold) near2 (rotat$3 or rotary)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 11:23
L11	1157	(semiconductor or wafer or substrate or workpiece) and (chamber or vessel or container or tank) with (nozzle or arm or sprayarm or manifold) near2 (rotat$3 or rotary)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 11:30
L12	676	11 and motor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 11:23
L13	645	12 and (chuck$3 or hold$3 or support$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:26
L14	282	(semiconductor or wafer or substrate or workpiece) with (nozzle or arm or sprayarm or manifold) near2 (rotat$3 or rotary) with around	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 11:31
L16	18	15 and (rotat$3 or rotary or revolve) and (arm or nozzle or sprayarm)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 15:25

5/17/06 4:39:57 PM
C:\Documents and Settings\JPerrin\My Documents\EAST\workspaces\10631378-wafer cleaner w rotary nozzles around wafer.wsp

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L20	9728	134/1,1.3,25.4,30,32,33,34,61, 172,184,186,902.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 15:25
L21	1487	20 and (rotat$3 or rotary) with (nozzle or arm or manifold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:25
L22	2484	20 and (rotat$3 or rotary or revolve) and (arm or nozzle or sprayarm)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 15:27
L23	1554	(semiconductor or wafer or substrate or workpiece) and 22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:27
L24	1390	23 and (chuck$3 or hold$3 or support$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:27
L25	1456	20 and (rotat$3 or rotary or revolve) with (arm or nozzle or sprayarm)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 15:27
L26	160	20 and (rotat$3 or rotary or revolve) with (arm or nozzle or sprayarm) with around	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 15:27
L27	948	(semiconductor or wafer or substrate or workpiece) and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:27
L28	868	27 and (chuck$3 or hold$3 or support$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:27